Leica DM8000M microscope

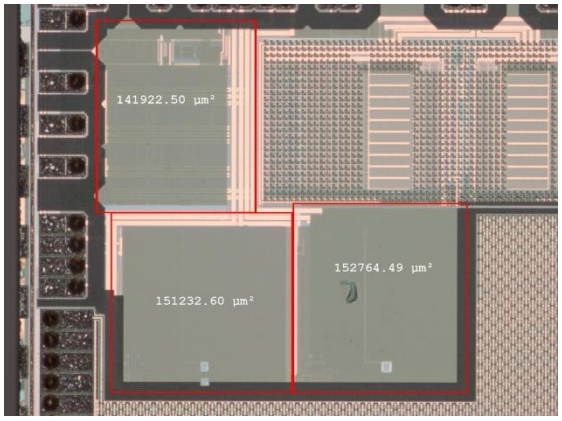
Capability/Application

The Leica DM8000 M features an integrated macro mode, giving you four times the field of view of conventional scanning objectives. Seeing more means faster throughput. The new Oblique UV (OUV) mode combines oblique illumination with UV light, which enables you to view a sample in top resolution from any angle – and enhances the accuracy of the inspection results. Applications include inspection, process control and defect analysis of wafers or material samples.

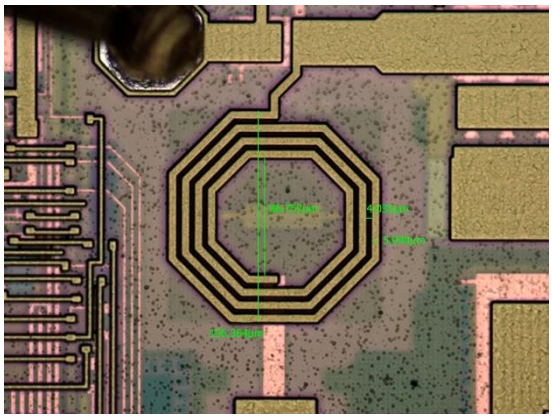
Specifications

Sample stage: capable of holding 8” wafer
Objectives: 0.7x (MACRO), 2.5x, 5x, 10x, 20x, 50x, 100x, 150x
Illumination: Visible/UV
Contrast method: Bright field/Dark field/Diffractive interference contrast
Digital camera: DFC295 (3M pixels)
Software: Leica LAS for measurements and live XYZ Builder, Leica MM for image assembly

Example application images



Circuit area measurement



On-chip component measurement

Equipment manufacturer web page

https://www.leica-microsystems.com/products/light-microscopes/p/leica-dm8000-m/

Youtube demo videos

https://www.youtube.com/watch?v=lvDUz_w7mSs&list=PLB04tRIZiriKo2vGuFjdqNh1kAimMPMEw